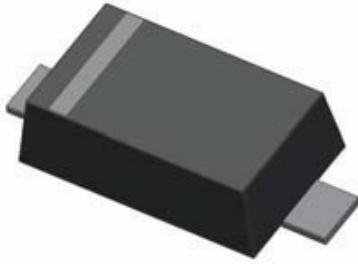




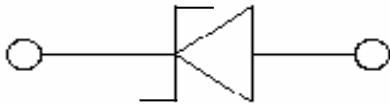
BZX584C2V4 THRU BZX584C75V

Zener Diode



Features

- High reliability
- Very sharp reverse characteristic
- Low reverse current level
- Zener Voltage 2.4V~47V



Mechanical Data

Package: SOD523

Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102

Polarity: Cathode line denotes the cathode end

Maximum Ratings (T_a=25 Unless otherwise specified Å

PARAMETER	SYMBOL	UNIT	VALUE
Power Dissipation at T _a =25	P _D	mW	200
Storage Temperature Range	T _{stg}	°C	-55~+150
Maximum Junction Temperature	T _J	°C	-55~+150
Maximum Regulator Current	I _{ZM}	mA	P _D /V _Z
Forward Voltage(@10mA)	V _F	V	1.0
Thermal Resistance Junction to Ambient Air*	R _{JA}	°C/W	625

Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
BZX584C2V4 THRU BZX584C75V	F2	Approximate 0.002	55	M		



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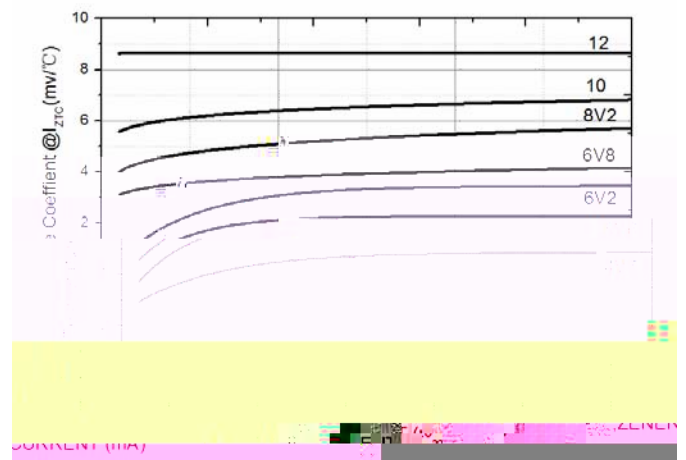
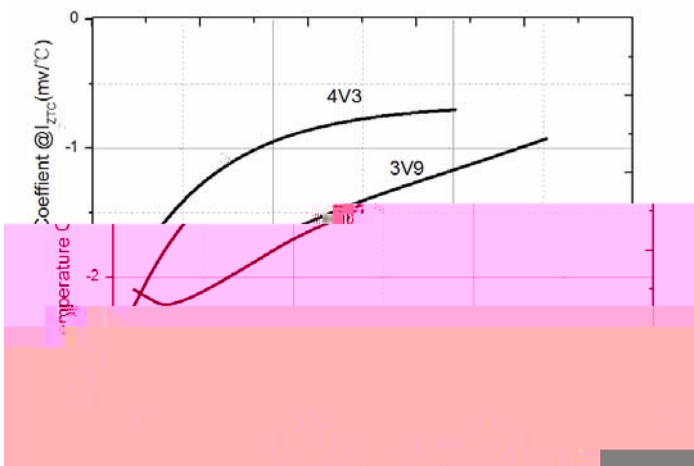
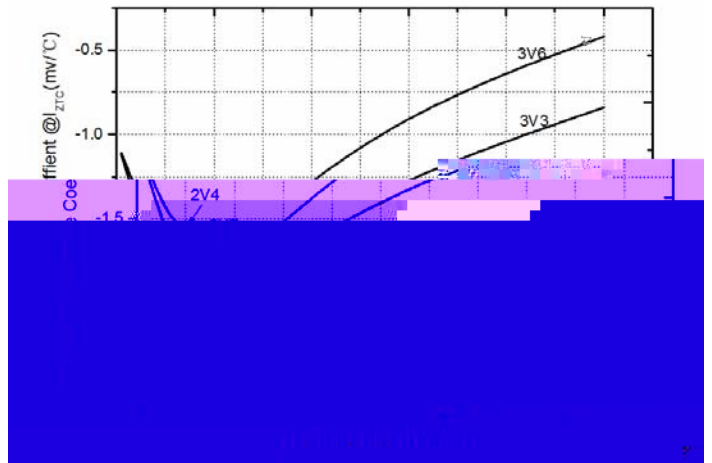
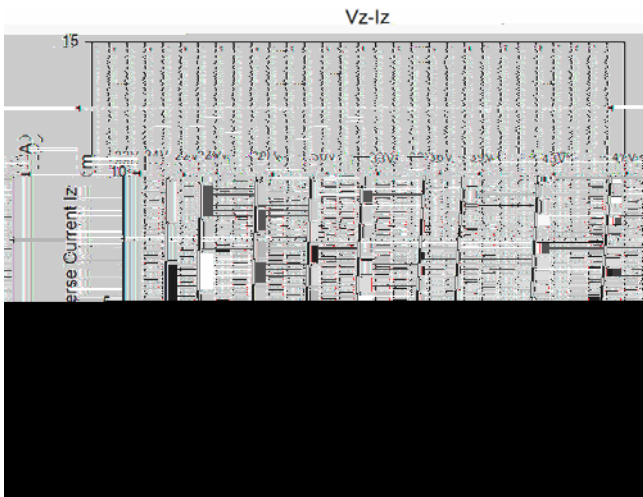
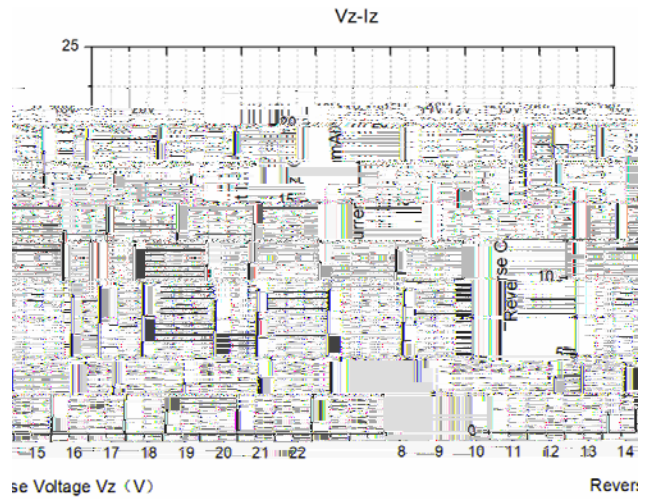
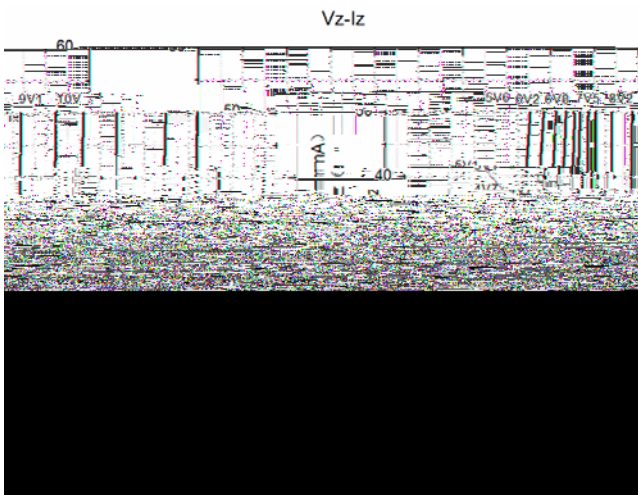
Electrical Characteristics $T_a=25$ Unless otherwise specified \dot{A}

Type Number	Device Marking	V_z at I_{zT} (V)			Z_{zt} (Ω)		Z_{zk} (Ω)		$I_R(\mu A)@V_R$	
		min.	typ.	max.	$I_{zT}(mA)$	max.	$I_{zk}(mA)$	max.	max	V_R



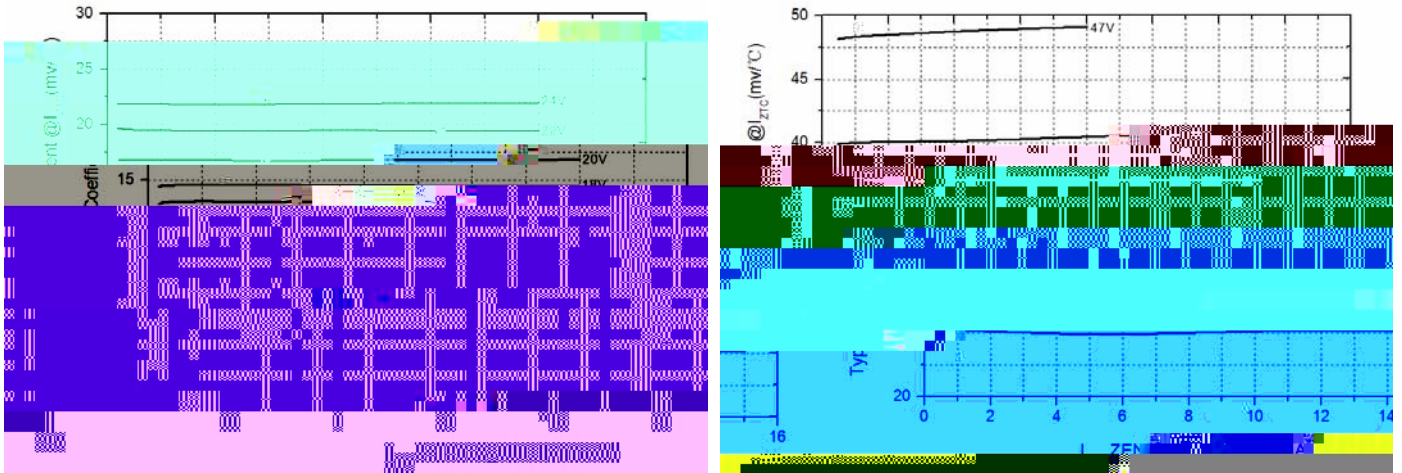
BZX584C2V4 THRU BZX584C75V

Characteristics (Typical)

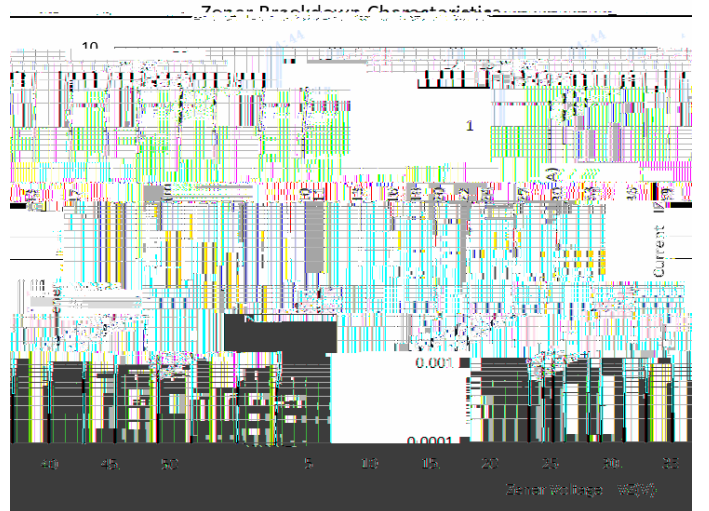
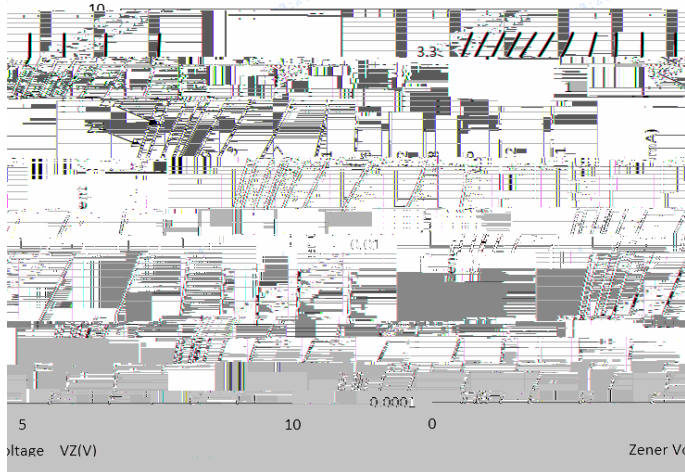




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Zener Breakdown Characteristics

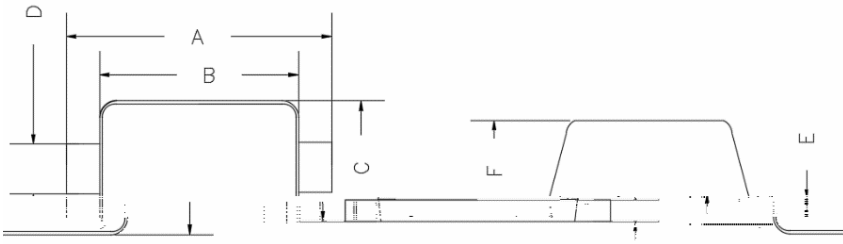




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Outline Dimensions

SOD-523



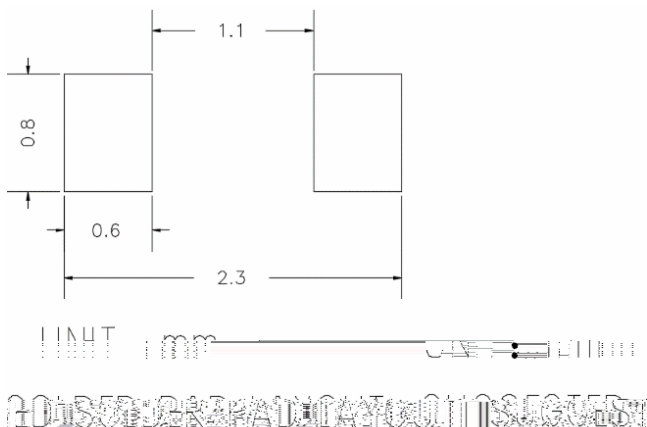
FRONT VIEW

RIGHT SIDE VIEW

TOP

DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	0.059	0.067	1.500	1.700
B	0.043	0.051	1.100	1.300
C	0.035	0.700	0.900	0.028
D	0.014	0.250	0.350	0.010
E	0.018	0.051	0.230	0.008

Soldering Footprint





BZX584C2V4 THRU BZX584C75V

Disclaimer

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment designed for special applications.